

<b>Company</b>		<b>DUNS#</b>	<b>URL For Additional Information</b>
National Semiconductor		04-147-2986	<a href="http://www.national.com/analog/quality/green">http://www.national.com/analog/quality/green</a>

<b>Contact</b>	<b>Title</b>	<b>Phone</b>	<b>Email</b>
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<b>Part Number</b>	<b>MSL Rating</b>	<b>Peak Body Temp C</b>	<b>MaxTime(Sec)</b>	<b>Cycles</b>	<b>Unit Type</b>
LM20323MHE NOPB	1	260	40	4	Each

<b>Document Date</b>	European RoHS Compliant. China RoHS Compliant.	<b>Weight (mg)</b>	Contains Halogens (Flame Retardant)
05-20-2009		73.06	

### Homogeneous Material Composition Declaration for Electronic Products

Item	Weight (mg)	Component	CAS#	Weight (mg)	Item-ppm	Part-ppm
Plastic	42.52	SiO2	60676-86-0	35.895	844,200	491,309
		Epoxy Resin	25928-94-3	6.378	150,000	87,298
		Sb2O3	1309-64-4	0.149	3,500	2,039
		Brominated Epoxy	40039-93-8	0.098	2,300	1,341
Leadframe	20.97	Cu	7440-50-8	20.173	962,000	276,116
		Ni	7440-02-0	0.629	30,000	8,609
		Si	7440-21-3	0.136	6,500	1,861
		Mg	7439-95-4	0.031	1,500	424
Chip	4.60	Si	7440-21-3	4.572	994,000	62,579
		Al	7429-90-5	0.028	6,000	383
Ext. LeadFinish	3.54	Sn	7440-31-5	3.540	1,000,000	48,453
Wires	0.50	Au	7440-57-5	0.500	1,000,000	6,844
Die Attach	0.49	Ag	7440-22-4	0.368	750,000	5,037
		Epoxy Resin	25928-94-3	0.123	250,000	1,684
Int. LeadFinish	0.44	Ag	7440-22-4	0.440	1,000,000	6,022

**Note:** The device content disclosed herewith is approximate and is based on engineering estimates only. It has not been verified through analytical. Additionally, the following should be noted:

- One or more dopant materials may be present in the silicon die at sub-ppm levels to provide semiconductor properties.
- Epoxy resin components listed are generic and may or may not be the specific compound used, which is considered proprietary.

### RoHS Material Composition Declaration


<b>RoHS Directive 2002/95/EC</b>	RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Cadmium
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Subject to the limitations below, National Semiconductor Corporation ("National") certifies the following information as of the document date.

- National products designated "ROHS Compliant" comply with the European Unions Directive on the Restriction of the Use of Hazardous Substances 2002/95/EC ("RoHS"). Certain National products contain lead in RoHS exempt applications 5, 7a or 7c.
- National products do not contain and are not manufactured with ozone depleting compounds.
- National products do not contain substances identified by the European Chemical Agency ("ECHA") as substances of very high concern ("SVHC").
- National products are manufactured in conformance with National specifications (SC)CSP-9-111C1 Supplier Environmental Requirements for Materials and Products and (SC)CSP-9-111S2 Banned and Reportable Substances.
- National's list of banned and reportable substances and management system is based on the current version of the Joint Industrial Guide, JIG-101.

National has taken commercially reasonable steps to provide representative and accurate information but may not have independently verified information provided or conducted chemical analysis of incoming materials. Equivalent compliant materials may have been substituted for those stated herein. Material concentrations are the maximum expected concentration of the substance in the device and may not represent the actual concentration. National and its suppliers consider certain limited information to be confidential and thus CAS numbers and other limited information may not be available for release. National's Standard Terms and Conditions of Sale apply to any issue arising out of or in connection with the information provided herein unless otherwise provided by a written contract signed by both parties.

NATIONAL ACCEPTS NO DUTY TO NOTIFY USERS OF THIS DECLARATION OF UPDATES OR CHANGES TO THIS DECLARATION.

 Gerry Edwards  
Vice President Quality

**Banned Substance Monitoring**

Part Number	Document Date
LM20323MHE NOPB	05-20-2009

European RoHS Compliant.

China RoHS Compliant.

Item#	Material	Cd	CrVI	Pb	Hg	PBB	PBDE	Cl	Br	Ref#
1	CHIP	<1	<1	<1	<30	<10	<10	NA	NA	1000
2	COMPOUND	< 2	< 2	< 2	< 2	< 5	< 5	< 50	< 50	127
3	EPOXY	<2	<5	<5	<1	<10	<10	NA	NA	32
4	EXTLF	< 2	< 2	23	< 2	NA	NA	NA	NA	595
5	FILM	< 2	< 2	< 2	< 2	< 5	< 5	120	< 50	626
6	FRAME	< 2	< 2	< 2	< 2	NA	NA	NA	NA	51
7	WIRE	< 2	< 2	< 2	< 2	NA	NA	NA	NA	75

\* Cd: Cadmium, CrVI: Hexavalent Chromium, Pb: Lead, Hg: Mercury, NA: Not Applicable

\* Unless otherwise noted, units are in PPM (parts-per-million)

Ref#	3rd Party Analysis (available upon request, subject to a non-disclosure agreement)
1000	Analysis on 03/01/2009 by BALAZ as per Report# E008516J #01/LMP7300D6/VIP050L23
127	Analysis on 03/01/2009 by SGS per Report# 04504/09
32	Analysis on 03/01/2009 by SGS per Report# ATJB/1331BS/2009
595	Analysis on 03/01/2009 by SGS per Report# 04501/09
626	Analysis on 03/01/2009 by SGS per Report# 04518/09
51	Analysis on 03/01/2009 by SGS per Report# 04535/09
75	Analysis on 03/01/2009 by SGS per Report# 04531/09